



LBL1
PCB Label
Size: 0.65" x 0.20 "

ZZ1 Label Assembly Note This Assembly Note is for PCB labels only

Variant	Label Text
001	ChangeMe!
002	ChangeMe!

Label Table

ZZ2 Assembly Note These assemblies are ESD sensitive, ESD precautions shall be observed.

1

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

D

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

			Number: PMP9496 Rev: E1	Designed for: Public Release Project Title: Automotive USB Cha Sheet Title:	Mod. Date: 1/6/2015	Texas
		y information contained therein. Texas Instruments and/or its licensors do no	SVN Rev: Not in version control	Assembly Variant: [No Variations]	Sheet:1 of 1	
		purpose, or will operate in an implementation. Texas Instruments and/or its esign implementation to confirm the system functionality for your application.	Drawn By: Engineer: Ambreesh Tripathi	File: Hardware_ANSI-B.SchDoc Contact: http://www.ti.com/support	Size: B	© Texas Instruments 2014
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